NCP5304

High Voltage, High and Low Side Driver

The NCP5304 is a High Voltage Power gate Driver providing two outputs for direct drive of 2 N−channel power MOSFETs or IGBTs arranged in a half−bridge configuration.

It uses the bootstrap technique to insure a proper drive of the High−side power switch. The driver works with 2 independent inputs with cross conduction protection.

Features

• High Voltage Range: up to 600 V
• dV/dt Immunity ±50 V/nsec
• Negative Current Injection Characterized Over the Temperature Range
• Gate Drive Supply Range from 10 V to 20 V
• High and Low Drive Outputs
• Output Source / Sink Current Capability 250 mA / 500 mA
• 3.3 V and 5 V Input Logic Compatible
• Up to VCC Swing on Input Pins
• Extended Allowable Negative Bridge Pin Voltage Swing to −10 V for Signal Propagation
• Matched Propagation Delays between Both Channels
• Outputs in Phase with the Inputs
• Cross Conduction Protection with 100 ns Internal Fixed Dead Time
• Under VCC LockOut (UVLO) for Both Channels
• Pin−to−Pin Compatible with Industry Standards
• These are Pb−Free Devices

Typical Applications

• Half−bridge Power Converters
• Full−bridge Converters

Features

MARKING DIAGRAMS

NCP5304 = Specific Device Code
A = Assembly Location
L or WL = Wafer Lot
Y or YY = Year
W or WW = Work Week
G or • = Pb−Free Package

PINOUT INFORMATION

ORDERING INFORMATION

<table>
<thead>
<tr>
<th>Device</th>
<th>Package</th>
<th>Shipping†</th>
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<tbody>
<tr>
<td>NCP5304PG</td>
<td>PDIP−8 (Pb−Free)</td>
<td>50 Units / Rail</td>
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<tr>
<td>NCP5304DR2G</td>
<td>SOIC−8 (Pb−Free)</td>
<td>2500 / Tape &amp; Reel</td>
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†For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specification Brochure, BRD8011/D.
Figure 1. Typical Application Resonant Converter (LLC type)

Figure 2. Typical Application Half Bridge Converter

Figure 3. Detailed Block Diagram
PIN DESCRIPTIONS

<table>
<thead>
<tr>
<th>Pin No.</th>
<th>Pin Name</th>
<th>Pin Function</th>
</tr>
</thead>
<tbody>
<tr>
<td>1</td>
<td>IN_LO</td>
<td>Logic Input for Low side driver output in phase</td>
</tr>
<tr>
<td>2</td>
<td>IN_HI</td>
<td>Logic Input for High side driver output in phase</td>
</tr>
<tr>
<td>3</td>
<td>VCC</td>
<td>Low side and main power supply</td>
</tr>
<tr>
<td>4</td>
<td>GND</td>
<td>Ground</td>
</tr>
<tr>
<td>5</td>
<td>DRV_LO</td>
<td>Low side gate drive output</td>
</tr>
<tr>
<td>6</td>
<td>BRIDGE</td>
<td>Bootstrap return or High side floating supply return</td>
</tr>
<tr>
<td>7</td>
<td>DRV_HI</td>
<td>High side gate drive output</td>
</tr>
<tr>
<td>8</td>
<td>VBOOT</td>
<td>Bootstrap power supply</td>
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MAXIMUM RATINGS

<table>
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<tr>
<th>Rating</th>
<th>Symbol</th>
<th>Value</th>
<th>Unit</th>
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<tr>
<td>VCC</td>
<td>Main power supply voltage</td>
<td>−0.3 to 20</td>
<td>V</td>
</tr>
<tr>
<td>VCC_transient</td>
<td>Main transient power supply voltage:</td>
<td>23</td>
<td>V</td>
</tr>
<tr>
<td></td>
<td>IVCC_max = 5 mA during 10 ms</td>
<td></td>
<td></td>
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<tr>
<td>VBRIDGE</td>
<td>VHV: High Voltage BRIDGE pin</td>
<td>−1 to 600</td>
<td>V</td>
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<tr>
<td>VBRIDGE</td>
<td>Allowable Negative Bridge Pin Voltage for IN_LO Signal Propagation to DRV_LO</td>
<td>−10</td>
<td>V</td>
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<tr>
<td></td>
<td>(see characterization curves for detailed results)</td>
<td></td>
<td></td>
</tr>
<tr>
<td>VBOOT-VBRIDGE</td>
<td>VHV: Floating supply voltage</td>
<td>−0.3 to 20</td>
<td>V</td>
</tr>
<tr>
<td>VDRV_HI</td>
<td>VHV: High side output voltage</td>
<td>VBRIDGE − 0.3 to VBOOT + 0.3</td>
<td>V</td>
</tr>
<tr>
<td>VDRV_LO</td>
<td>Low side output voltage</td>
<td>−0.3 to VCC + 0.3</td>
<td>V</td>
</tr>
<tr>
<td>dVBRIDGE/dt</td>
<td>Allowable output slew rate</td>
<td>50</td>
<td>V/ns</td>
</tr>
<tr>
<td>VIN_XX</td>
<td>Inputs IN_HI, IN_LO</td>
<td>−1.0 to VCC + 0.3</td>
<td>V</td>
</tr>
</tbody>
</table>

ESD Capability:
- HBM model (all pins except pins 6–7–8 in 8 pins package or 11–12–13 in 14 pins package) | 2 | kV |
- Machine model (all pins except pins 6–7–8 in 8 pins package or 11–12–13 in 14 pins package) | 200 | V |

Latch up capability per Jedec JESD78

RJA

Power dissipation and Thermal characteristics
- PDIP–8: Thermal Resistance, Junction–to–Air | 100 | °C/W |
- SO–8: Thermal Resistance, Junction–to–Air | 178 | °C/W |

TJ_max

Maximum Operating Junction Temperature | +150 | °C |

Stresses exceeding those listed in the Maximum Ratings table may damage the device. If any of these limits are exceeded, device functionality should not be assumed, damage may occur and reliability may be affected.
## ELECTRICAL CHARACTERISTIC

(V\textsubscript{CC} = V\textsubscript{boot} = 15 V, V\textsubscript{GND} = V\textsubscript{bridge}, −40°C < T\textsubscript{J} < 125°C, Outputs loaded with 1 nF)

<table>
<thead>
<tr>
<th>Rating</th>
<th>Symbol</th>
<th>T\textsubscript{J} −40°C to 125°C</th>
</tr>
</thead>
<tbody>
<tr>
<td></td>
<td></td>
<td>Min</td>
</tr>
<tr>
<td></td>
<td></td>
<td>Units</td>
</tr>
</tbody>
</table>

### OUTPUT SECTION

- **Output high short circuit pulsed current** V\textsubscript{DRV} = 0 V, PW ≤ 10 μs (Note 1)
  - Symbol: I\textsubscript{DRVsource} 
  - Min: – 250 – mA
- **Output low short circuit pulsed current** V\textsubscript{DRV} = V\textsubscript{CC}, PW ≤ 10 μs (Note 1)
  - Symbol: I\textsubscript{DRVsink} 
  - Min: – 500 – mA
- **Output resistor (Typical value @ 25°C)** Source
  - Symbol: R\textsubscript{OH} 
  - Min: – 30 – 60 Ω
- **Output resistor (Typical value @ 25°C)** Sink
  - Symbol: R\textsubscript{OL} 
  - Min: – 10 – 20 Ω
- **High level output voltage**, V\textsubscript{BIAS−VDRV_XX} @ I\textsubscript{DRV_XX} = 20 mA
  - Symbol: V\textsubscript{DRV_H} 
  - Min: – 0.7 – 1.6 V
- **Low level output voltage**, V\textsubscript{DRV_XX} @ I\textsubscript{DRV_XX} = 20 mA
  - Symbol: V\textsubscript{DRV_L} 
  - Min: – 0.2 – 0.6 V

### DYNAMIC OUTPUT SECTION

- **Turn−on propagation delay** (V\textsubscript{bridge} = 0 V)
  - Symbol: t\textsubscript{ON} 
  - Min: – 100 – 170 ns
- **Turn−off propagation delay** (V\textsubscript{bridge} = 0 V or 50 V) (Note 2)
  - Symbol: t\textsubscript{OFF} 
  - Min: – 100 – 170 ns
- **Output voltage rise time** (from 10% to 90% @ V\textsubscript{CC} = 15 V) with 1 nF load
  - Symbol: tr 
  - Min: – 85 – 160 ns
- **Output voltage fall time** (from 90% to 10% @V\textsubscript{CC} = 15 V) with 1 nF load
  - Symbol: tf 
  - Min: – 35 – 75 ns
- **Propagation delay matching between the High side and the Low side** @ 25°C (Note 3)
  - Symbol: Δt 
  - Min: – 20 – 35 ns
- **Internal fixed dead time** (Note 4)
  - Symbol: DT 
  - Min: 65 – 100 – 190 ns
- **Minimum input width that changes the output**
  - Symbol: t\textsubscript{PW1} 
  - Min: – – 50 ns
- **Maximum input width that does not change the output**
  - Symbol: t\textsubscript{PW2} 
  - Min: 20 – – ns

### INPUT SECTION

- **Low level input voltage threshold**
  - Symbol: V\textsubscript{IN} 
  - Min: – – 0.8 V
- **Input pull−down resistor** (V\textsubscript{IN} < 0.5 V)
  - Symbol: R\textsubscript{IN} 
  - Min: – 200 – kΩ
- **High level input voltage threshold**
  - Symbol: V\textsubscript{IN} 
  - Min: 2.3 – – V
- **Logic “1” input bias current** @ V\textsubscript{IN_XX} = 5 V @ 25°C
  - Symbol: I\textsubscript{IN+} 
  - Min: – 5 – 25 μA
- **Logic “0” input bias current** @ V\textsubscript{IN_XX} = 0 V @ 25°C
  - Symbol: I\textsubscript{IN−} 
  - Min: – – 2.0 μA

### SUPPLY SECTION

- **V\textsubscript{CC} UV Start−up voltage threshold**
  - Symbol: V\textsubscript{CC_stup} 
  - Min: 8.0 – 8.9 – 9.9 V
- **V\textsubscript{CC} UV Shut−down voltage threshold**
  - Symbol: V\textsubscript{CC_shtdwn} 
  - Min: 7.3 – 8.2 – 9.1 V
- **Hysteresis on V\textsubscript{CC}**
  - Symbol: V\textsubscript{CC_hyst} 
  - Min: 0.3 – 0.7 – V
- **V\textsubscript{boot} Start−up voltage threshold reference to bridge pin** (V\textsubscript{boot_stup} = V\textsubscript{bo} – V\textsubscript{bridge})
  - Symbol: V\textsubscript{boot_stup} 
  - Min: 8.0 – 8.9 – 9.9 V
- **V\textsubscript{boot} UV Shut−down voltage threshold**
  - Symbol: V\textsubscript{boot_shtdwn} 
  - Min: 7.3 – 8.2 – 9.1 V
- **Hysteresis on V\textsubscript{boot}**
  - Symbol: V\textsubscript{boot_shtdwn} 
  - Min: 0.3 – 0.7 – V
- **Leakage current on high voltage pins to GND** (V\textsubscript{BOOT} = V\textsubscript{BRIDGE} = DRV_HI = 600 V)
  - Symbol: I\textsubscript{HV_LEAK} 
  - Min: – 5 – 40 μA
- **Consumption in active mode** (V\textsubscript{CC} = V\textsubscript{bo}, f\textsubscript{sw} = 100 kHz and 1 nF load on both driver outputs)
  - Symbol: ICC1 
  - Min: – – 4 – 5 mA
- **Consumption in inhibition mode** (V\textsubscript{CC} = V\textsubscript{bo})
  - Symbol: ICC2 
  - Min: – 250 – 400 μA
- **V\textsubscript{CC} current consumption in inhibition mode**
  - Symbol: ICC3 
  - Min: – 200 – μA
- **V\textsubscript{boot} current consumption in inhibition mode**
  - Symbol: ICC4 
  - Min: – 50 – μA

1. Parameter guaranteed by design
2. Turn−off propagation delay @ V\textsubscript{bridge} = 600 V is guaranteed by design
3. See characterization curve for Δt parameters variation on the full range temperature.
4. Timing diagram definition see Figure 7.
5. Timing diagram definition see Figure 5 and Figure 6.

Product parametric performance is indicated in the Electrical Characteristics for the listed test conditions, unless otherwise noted. Product performance may not be indicated by the Electrical Characteristics if operated under different conditions.
Figure 4. Input/Output Timing Diagram

Figure 5. Propagation Delay and Rise / Fall Time Definition

Figure 6. Matching Propagation Delay
Figure 7. Input/Output Cross Conduction Output Protection Timing Diagram
CHARACTERIZATION CURVES

Figure 8. Turn ON Propagation Delay vs. Supply Voltage ($V_{CC} = V_{BOOT}$)

Figure 9. Turn ON Propagation Delay vs. Temperature

Figure 10. Turn OFF Propagation Delay vs. Supply Voltage ($V_{CC} = V_{BOOT}$)

Figure 11. Turn OFF Propagation Delay vs. Temperature

Figure 12. High Side Turn ON Propagation Delay vs. VBRIDGE Voltage

Figure 13. High Side Turn OFF Propagation Delay vs. VBRIDGE Voltage
Figure 14. Turn ON Risetime vs. Supply Voltage ($V_{CC} = V_{BOOT}$)

Figure 15. Turn ON Risetime vs. Temperature

Figure 16. Turn OFF Falltime vs. Supply Voltage ($V_{CC} = V_{BOOT}$)

Figure 17. Turn OFF Falltime vs. Temperature

Figure 18. Propagation Delay Matching Between High Side and Low Side Driver vs. Temperature

Figure 19. Dead Time vs. Temperature
Figure 20. Low Level Input Voltage Threshold vs. Supply Voltage ($V_{CC} = V_{BOOT}$)

Figure 21. Low Level Input Voltage Threshold vs. Temperature

Figure 22. High Level Input Voltage Threshold vs. Supply Voltage ($V_{CC} = V_{BOOT}$)

Figure 23. High Level Input Voltage Threshold vs. Temperature

Figure 24. Logic “0” Input Current vs. Supply Voltage ($V_{CC} = V_{BOOT}$)

Figure 25. Logic “0” Input Current vs. Temperature
Figure 26. Logic “1” Input Current vs. Supply Voltage (VCC = VBOOT)

Figure 27. Logic “1” Input Current vs. Temperature

Figure 28. Low Level Output Voltage vs. Supply Voltage (VCC = VBOOT)

Figure 29. Low Level Output Voltage vs. Temperature

Figure 30. High Level Output Voltage vs. Supply Voltage (VCC = VBOOT)

Figure 31. High Level Output Voltage vs. Temperature
Figure 32. Output Source Current vs. Supply Voltage ($V_{CC} = V_{BOOT}$)

Figure 33. Output Source Current vs. Temperature

Figure 34. Output Sink Current vs. Supply Voltage ($V_{CC} = V_{BOOT}$)

Figure 35. Output Sink Current vs. Temperature

Figure 36. Leakage Current on High Voltage Pins (600 V) to Ground vs. $V_{BRIDGE}$ Voltage ($V_{BRIDGE} = V_{BOOT} = V_{DRV_HI}$)

Figure 37. Leakage Current on High Voltage Pins (600 V) to Ground vs. Temperature ($V_{BRIDGE} = V_{BOOT} = V_{DRV_HI} = 600 V$)
Figure 38. $V_{BOOT}$ Supply Current vs. Bootstrap Supply Voltage

Figure 39. $V_{BOOT}$ Supply Current vs. Temperature

Figure 40. $V_{CC}$ Supply Current vs. $V_{CC}$ Supply Voltage

Figure 41. $V_{CC}$ Supply Current vs. Temperature

Figure 42. UVLO Startup Voltage vs. Temperature

Figure 43. UVLO Shutdown Voltage vs. Temperature
Figure 44. ICC1 Consumption vs. Switching Frequency with 15 nC Load on Each Driver @ VCC = 15 V

Figure 45. ICC1 Consumption vs. Switching Frequency with 33 nC Load on Each Driver @ VCC = 15 V

Figure 46. ICC1 Consumption vs. Switching Frequency with 50 nC Load on Each Driver @ VCC = 15 V

Figure 47. ICC1 Consumption vs. Switching Frequency with 100 nC Load on Each Driver @ VCC = 15 V

Figure 48. NCP5304, Negative Voltage Safe Operating Area on the Bridge Pin
APPLICATION INFORMATION

Negative Voltage Safe Operating Area

When the driver is used in a half bridge configuration, it is possible to see negative voltage appearing on the bridge pin (pin 6) during the power MOSFETs transitions. When the high−side MOSFET is switched off, the body diode of the low−side MOSFET starts to conduct. The negative voltage applied to the bridge pin thus corresponds to the forward voltage of the body diode. However, as pcb copper tracks and wire bonding introduce stray elements (inductance and capacitor), the maximum negative voltage of the bridge pin will combine the forward voltage and the oscillations created by the parasitic elements. As any CMOS device, the deep negative voltage of a selected pin can inject carriers into the substrate, leading to an erratic behavior of the concerned component. ON Semiconductor provides characterization data of its half−bridge driver to show the maximum negative voltage the driver can safely operate with. To prevent the negative injection, it is the designer duty to verify that the amount of negative voltage pertinent to his/her application does not exceed the characterization curve we provide, including some safety margin.

In order to estimate the maximum negative voltage accepted by the driver, this parameter has been characterized over full the temperature range of the component. A test fixture has been developed in which we purposely negatively bias the bridge pin during the freewheel period of a buck converter. When the upper gate voltage shows signs of an erratic behavior, we consider the limit has been reached.

Figure 48, illustrates the negative voltage safe operating area. Its interpretation is as follows: assume a negative 10 V pulse featuring a 100 ns width is applied on the bridge pin, the driver will work correctly over the whole die temperature range. Should the pulse swing to −20 V, keeping the same width of 100 ns, the driver will not work properly or will be damaged for temperatures below 125°C.

Summary:

- If the negative pulse characteristic (negative voltage level & pulse width) is above the curves the driver runs in safe operating area.
- If the negative pulse characteristic (negative voltage level and pulse width) is below one or all curves the driver will NOT run in safe operating area.

Note, each curve of the Figure 48 represents the negative voltage and width level where the driver starts to fail at the corresponding die temperature.

If in the application the bridge pin is too close of the safe operating limit, it is possible to limit the negative voltage to the bridge pin by inserting one resistor and one diode as follows:

![Diagram](image.png)

R1 and D1 should be placed as close as possible of the driver. D1 should be connected directly between the bridge pin (pin 6) and the ground pin (pin 4). By this way the negative voltage applied to the bridge pin will be limited by D1 and R1 and will prevent any wrong behavior.
PACKAGING DIMENSIONS

8 LEAD PDIP
CASE 626−05
ISSUE N

NOTES:
2. CONTROLLING DIMENSION: INCHES.
3. DIMENSIONS A, A1 AND L ARE MEASURED WITH THE PACK-
AGE SEATED IN JEDEC SEATING PLANE GAUGE GS−3.
4. DIMENSIONS D, D1 AND E1 DO NOT INCLUDE MOLD FLASH
OR PROTRUSIONS. MOLD FLASH OR PROTRUSIONS ARE NOT
TO EXCEED 0.10 INCH.
5. DIMENSION E IS MEASURED AT A POINT 0.015 BELOW DATUM
PLANE H WITH THE LEADS CONSTRAINED PERPENDICULAR
TO DATUM C.
6. DIMENSION E3 IS MEASURED AT THE LEAD TIPS WITH THE
LEADS UNCONSTRAINED.
7. DATUM PLANE H IS COINCIDENT WITH THE BOTTOM OF THE
LEADS, WHERE THE LEADS EXIT THE BODY.
8. PACKAGE CONTOUR IS OPTIONAL (ROUNDED OR SQUARE
CORNERS).

<table>
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<tr>
<th>DIMENSIONS</th>
<th>INCHES</th>
<th>MILLIMETERS</th>
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<tbody>
<tr>
<td>A</td>
<td>0.218</td>
<td>5.53</td>
</tr>
<tr>
<td>A1</td>
<td>0.015</td>
<td>0.38</td>
</tr>
<tr>
<td>A2</td>
<td>0.195</td>
<td>4.95</td>
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<tr>
<td>b</td>
<td>0.014</td>
<td>0.36</td>
</tr>
<tr>
<td>b2</td>
<td>0.060</td>
<td>1.52</td>
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<tr>
<td>C</td>
<td>0.014</td>
<td>0.36</td>
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<tr>
<td>D</td>
<td>0.400</td>
<td>1.01</td>
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<tr>
<td>D1</td>
<td>0.025</td>
<td>0.64</td>
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<tr>
<td>E</td>
<td>0.320</td>
<td>8.13</td>
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<tr>
<td>E1</td>
<td>0.240</td>
<td>6.10</td>
</tr>
<tr>
<td>e</td>
<td>0.100</td>
<td>2.54</td>
</tr>
<tr>
<td>eB</td>
<td>0.433</td>
<td>10.99</td>
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<tr>
<td>L</td>
<td>0.115</td>
<td>2.92</td>
</tr>
<tr>
<td>M</td>
<td>0.115</td>
<td>2.92</td>
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NCP5304

PACKAGE DIMENSIONS

SOIC−8 NB
CASE 751−07
ISSUE AK

NOTES:
2. CONTROLLING DIMENSION: MILLIMETER.
3. DIMENSION A AND B DO NOT INCLUDE MOLD PROTRUSION.
4. MAXIMUM MOLD PROTRUSION 0.15 (0.006) PER SIDE.
5. DIMENSION D DOES NOT INCLUDE DAMBAR PROTRUSION. ALLOWABLE DAMBAR PROTRUSION SHALL BE 0.127 (0.005) TOTAL IN EXCESS OF THE D DIMENSION AT MAXIMUM MATERIAL CONDITION.
6. 751−01 THRU 751−06 ARE OBSOLETE. NEW STANDARD IS 751−07.

<table>
<thead>
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<td>D</td>
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<td>E</td>
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<td>F</td>
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<td>G</td>
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<tr>
<td>N</td>
<td>0.25</td>
</tr>
<tr>
<td>S</td>
<td>5.00</td>
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*For additional information on our Pb−Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

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